Hewlett Packard Enterprise

Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model **[List multiple models if applicable.]**
HPE FlexFabric 12902E Switch Chassis(JH345A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	7
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

HPE instructions for this template are available at MF877-01

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Extract all of the part 2.
2. Unscrew the screws on part 3, and then remove part 3.
3. Extract all of the part 4.
4. Remove part 5 from chassis 1.
5. Remove part 13 from chassis 1.
6. Extract all of the part 14.
7. Unscrew the screws on part 6, and then remove part 6.
8. Extract all of the part 10.
9. Extract all of the part 11.
10. Unscrew the screws on part 7, and then remove part 7.
11. Remove part 8 from chassis 1.
12. Remove part 9 from chassis 1.
13. Remove pcb 12 from chassis 1.
14. Unscrew the screws on part 7-2, and then remove part 7-2.
15. Extract all of the part 7-1.
16. Remove part 7-3 from part 7-5.
17. Remove part 7-4 from part 7-5.
18. Remove part 7-3-2 from part 7-3-1 and remove pcb 7-3-3 from part 7-3-1.
19. Remove part 7-4-2 from part 7-4-1 and remove pcb 7-4-3 from part 7-4-1.
20. Remove part 7-5-1 from pcb 7-5-2 and remove pcb 7-5-2 from part 7-5-3.
21. Remove part 7-5-4 from part 7-5-5 and remove part 7-5-5.
22. Remove part 7-5-6 from pcb 7-5-7 and remove pcb 7-5-7 from part 7-5-8.
23. Remove part 7-5-9 from pcb 7-5-11 and remove part 7-5-10 from pcb 7-5-11.
24. Remove part 7-5-11 from part 7-5-12.
25. Unscrew the screws on pcb 11-1, and then remove pcb 11-1 from 11-5.
26. Remove part 11-2 from pcb 11-1.
27. Remove pcb 11-3 from part 11-5.
28. Remove pcb 11-4 from part 11-5.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

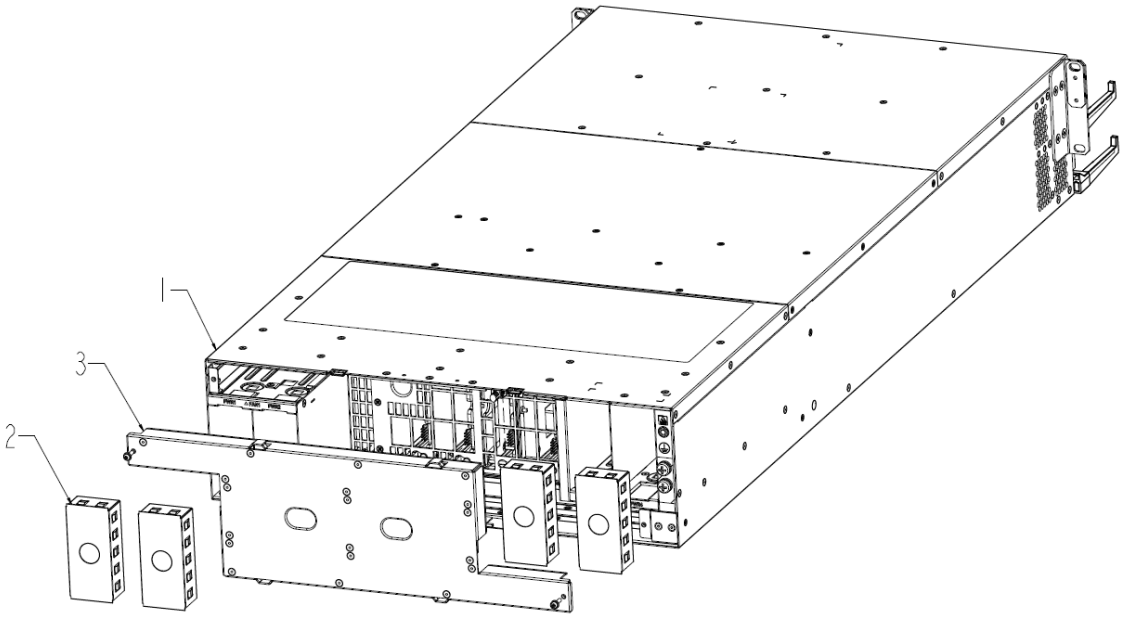

Figure 1 Treatments to the product (rear view)

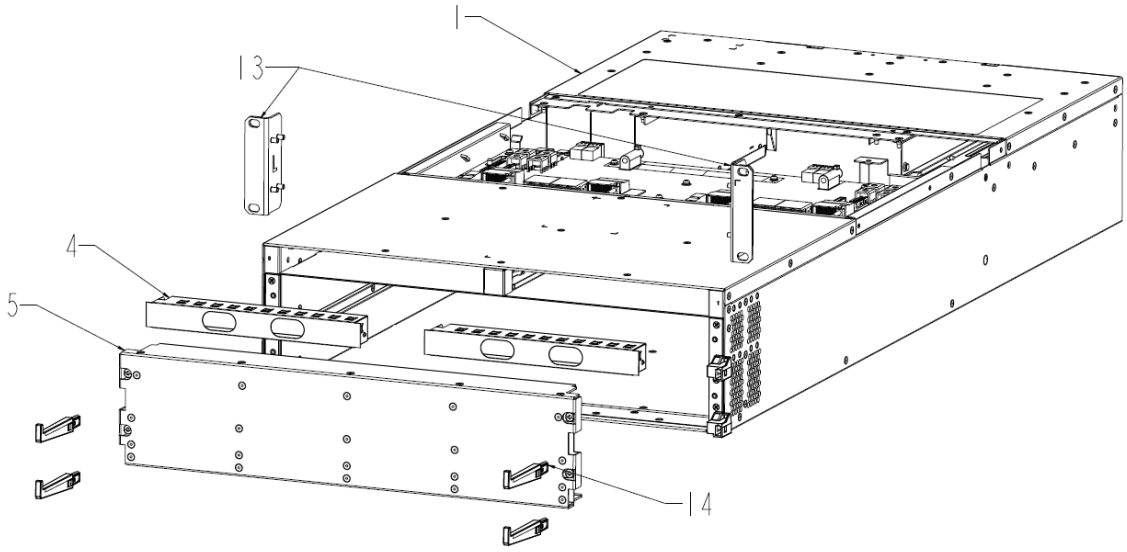

Figure 2 Treatments to the product（front view）

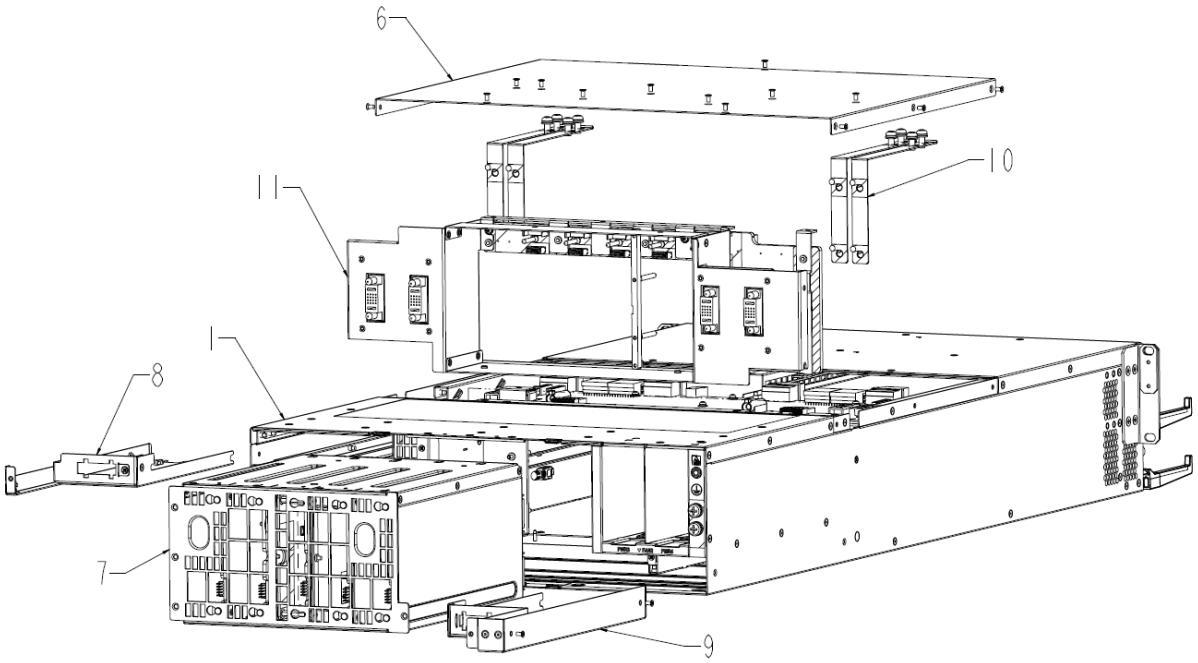

Figure 3 Treatments to the product（rear view）

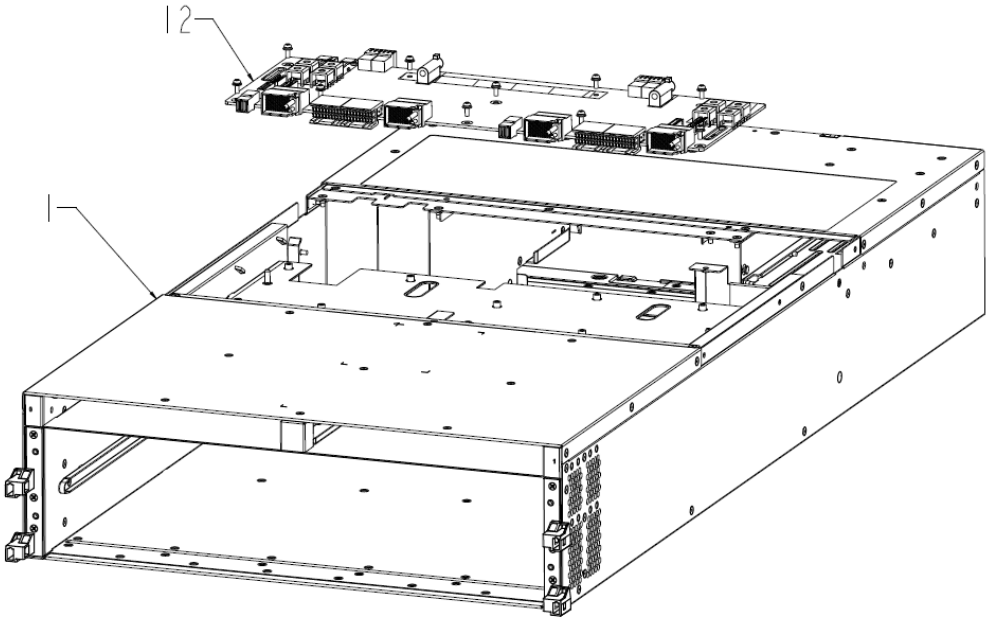

Figure 4 Treatments to the product（front view）

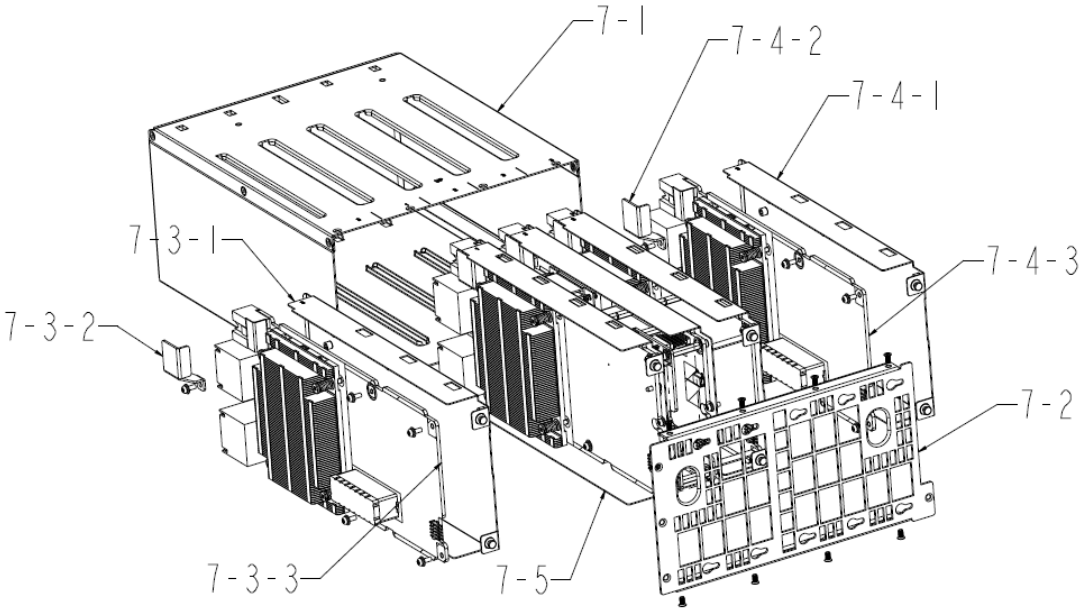

Figure 5 Treatments to part 7

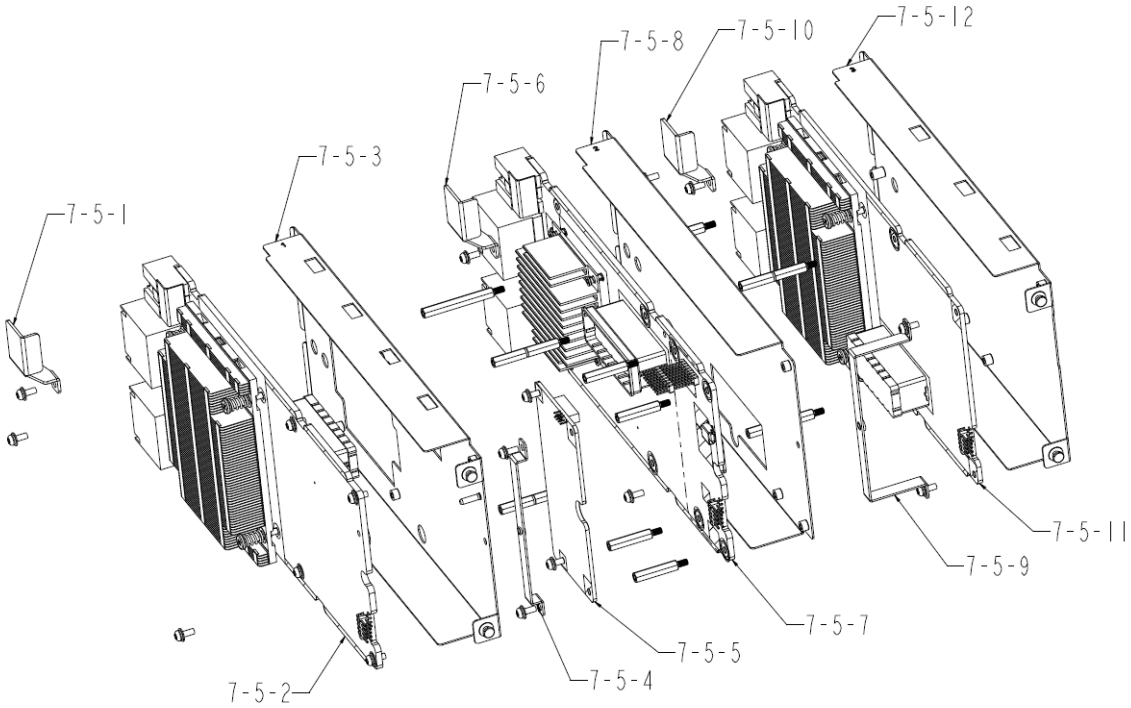

Figure 6 Treatments to part 7-5

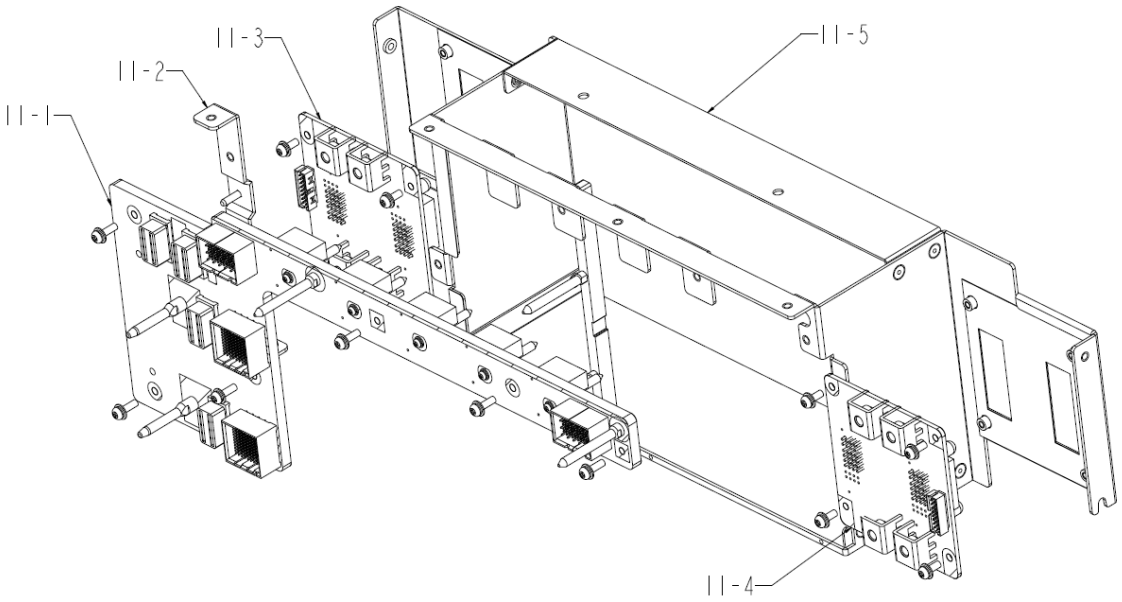

Figure 7 Treatments to part 11

3.3 Material of the facility built

Facility	Components	Material	Weight (g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe	17364	56.80%		Fe recycling
2		Fe	30*4	0.39%		Fe recycling
3		Fe	800	2.62%		Fe recycling
4		Fe	50*2	0.33%		Fe recycling
5		Fe	2030	6.64%		Fe recycling
6		Fe	1240	4.06%		Fe recycling
7	7-1	Fe	1300	4.25%		Fe recycling
	7-2	Fe	218	0.71%		Fe recycling
	7-3	Fe,Complex PCB	989	3.24%		Fe recycling
	7-4	Fe,Complex PCB	2877	9.41%		Fe recycling
	7-5	Fe,Complex PCB	989	3.24%		Fe recycling
8		Fe	224	0.73%		Fe recycling
9		Fe	342	1.12%		Fe recycling
10		Cu	3*4	0.04%		Cu recycling
11	11-1	Complex PCB	260	0.85%		
	11-2	Fe	27	0.09%		Fe recycling
	11-3	Complex PCB	80	0.26%		
	11-4	Complex PCB	80	0.26%		
	11-5	Fe	763	2.50%		Fe recycling
12		Complex PCB	570	1.77%		
13		Fe	150	0.49%		Fe recycling
14		Zn,Fe	9*4	0.12%		Zn recycling Fe recycling

4. Revised record

Date	Version	Author	Modify content
2016.9.20	V0	Pan.Yujiao	Initial version